

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)

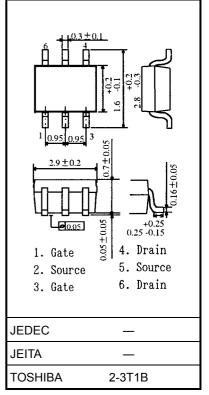
# **TPC6201**

## HDD Motor Drive Applications Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance:  $R_{DS}$  (ON) = 80 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 3.8 \text{ S} (typ.)$
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement-model:  $V_{th}$  = 1.3 to 2.5 V ( $V_{DS}$  = 10 V,  $I_D$  = 1 mA)

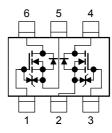
#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	30	V	
Drain-gate vo	ltage (R <sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	30	V	
Gate-source	voltage	V <sub>GSS</sub>	±20	V	
Drain	DC (Note 1)	Ι <sub>D</sub>	2.5	А	
current	Pulse (Note 1)	I <sub>DP</sub>	10	~	
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P <sub>D</sub> (1)	0.9	w	
	Single device value at dual operation (Note 3b)	P <sub>D</sub> (2)	0.76		
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D</sub> (1)	0.4	W	
	Single device value at dual operation (Note 3b)	P <sub>D</sub> (2)	0.31		
Single pulse avalanche energy (Note 4)		E <sub>AS</sub>	1.0	mJ	
Avalanche cu	rrent	I <sub>AR</sub>	1.25	А	
Repetitive ava	alanche energy (Note 5)	E <sub>AR</sub>	0.16	mJ	
Channel temp	perature	T <sub>ch</sub>	150	°C	
Storage temp	erature range	T <sub>stg</sub>	–55 to 150	°C	



Weight: 0.011 g (typ.)

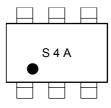
## **Circuit Configuration**



## **Thermal Characteristics**

Chara	Symbol	Max	Unit		
Thermal Resistance (channel-to-ambient) (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (2)	139	°C/W	
	Single device value at dual operation (Note 3b)	R <sub>th (ch-a)</sub> (2)	165		
Thermal Resistance	Single-device operation (Note 3a)	R <sub>th (ch-a)</sub> (2)	310	°C/W	
(channel-to-ambient) (t = 5 s) (Note 2b)	Single device value at dual operation (Note 3b)	R <sub>th (ch-a)</sub> (2)	400		

Marking (Note 6)



Note: (Note 1), (Note 2), (Note 3), (Note 4), (Note 5), (Note 6) Please see next page.

This transistor is an electrostatically sensitive device. Please handle it with caution.

Unit: mm

**Electrical Characteristics (Ta = 25°C)** 

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage current		I <sub>GSS</sub>	$V_{GS}=\pm 16~V,~V_{DS}=0~V$			±10	μA	
Drain cut-OFF cu	rrent	I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			10	μA	
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30			V	
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	_		v	
Gate threshold ve	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.3	_	2.5	V	
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 1.3 \text{ A}$		128	145	mΩ	
		R <sub>DS (ON)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 1.3 \text{ A}$		80	95		
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1.3 \text{ A}$	1.25	3.8		S	
Input capacitance		C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	170	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>			25			
Output capacitance		C <sub>oss</sub>			40			
Switching time	Rise time	tr	$V_{GS} \stackrel{10}{}_{0}V \int I_{D} = 1.3 \text{ A}$	_	2.4	_	ns	
	Turn-ON time	t <sub>on</sub>		_	8	_		
	Fall time	t <sub>f</sub>		_	2	_		
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \simeq 15 \text{ V}$ Duty $\leq 1\%$ , t <sub>w</sub> = 10 µs	_	11	_		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 24 \text{ V}, \text{ V}_{GS} = 10 \text{ V},$	_	4.7	_	nC	
Gate-source charge		Q <sub>gs</sub>	$I_{\rm D} = 2.5 \rm{A}$		3.4			
Gate-drain ("miller") charge		Q <sub>gd</sub>			1.3			

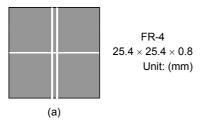
#### Source-Drain Ratings and Characteristics (Ta = 25°C)

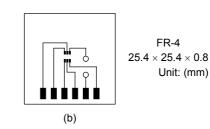
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Pulse drain reverse current (Note	1) I <sub>DRP</sub>	—	_	_	10	А
Forward voltage (diode)	V <sub>DSF</sub>	$I_{DR} = 2.5 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.2	V

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)

(b) Device mounted on a glass-epoxy board (b) (t = 5 s)



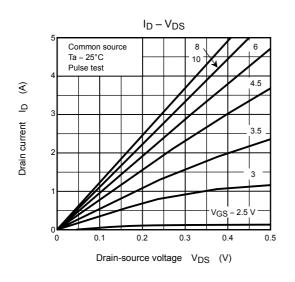


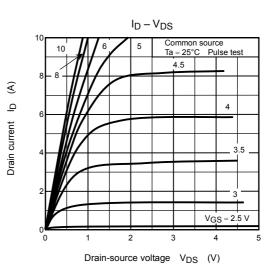
Note 3: (a) Single-device operation; values of P<sub>D</sub> (1) and R<sub>th (ch-a)</sub> (1) for a single device during single-device operation

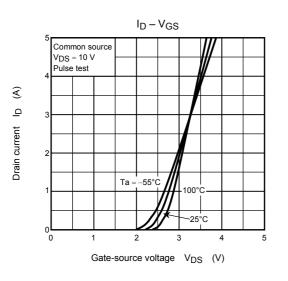
(b) Dual operation; values of  $P_D$  (2) and  $R_{th (ch-a)}$  (2) for a single device during dual operation

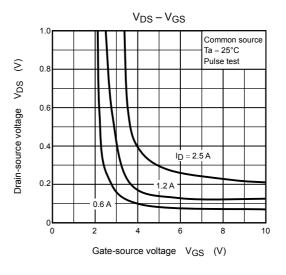
- Note 4:  $V_{DD} = 24 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.5 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 1.25 A
- Note 5: Repetitive rating; pulse width limited by maximum channel temperature
- Note 6: Black round marking "•" locates on the left lower side of parts number marking "S4A" indicates terminal No.1.

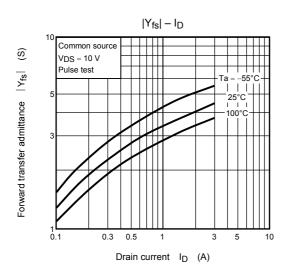
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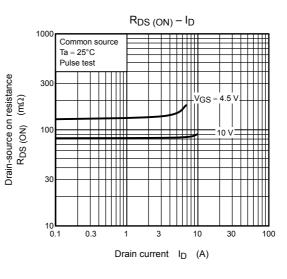




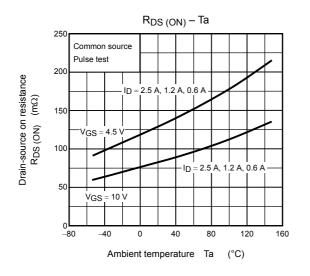


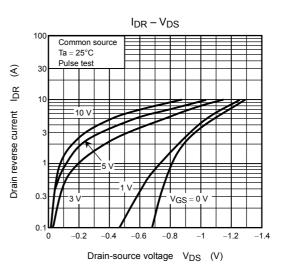


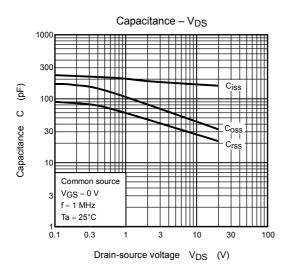


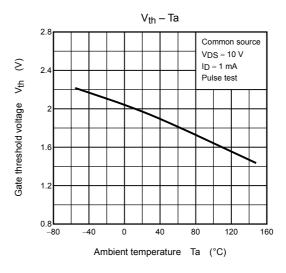


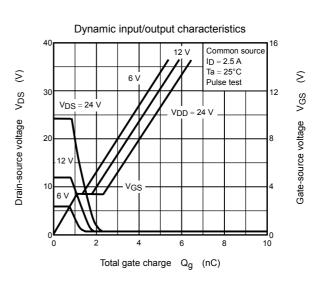
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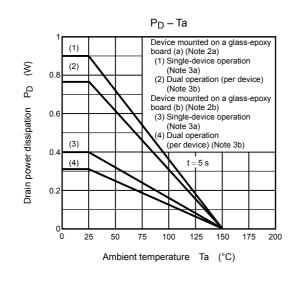


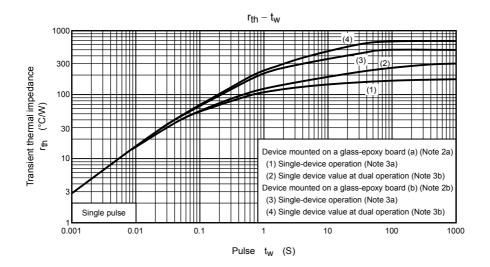




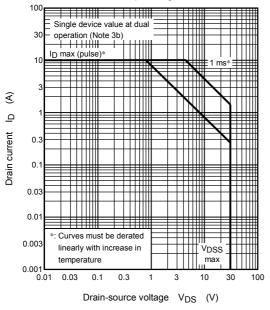








Safe operating area



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